

Description

Method of Manufacturing a Semiconductor Device and a Method for Fixing the Semiconductor Device Using Substrate Jig

CROSS REFERENCE TO RELATED APPLICATIONS

[0001] This application is a divisional application of Serial No.

Now Pater No. 6, 75% 074

10/101,169 filed March 20, 2002

BACKGROUND OF THE INVENTION

[0002] This application claims the benefit of a Japanese Patent Application No. 2001–322811 filed Oct. 19, 2001 in the Japanese Patent Office, the disclosure of which is hereby incorporated by reference.

1. FIELD OF THE INVENTION

[0003] The present invention generally relates to jigs for semiconductor substrates and methods for manufacturing semiconductor devices using the same, and more particularly to a method of manufacturing a semiconductor de-